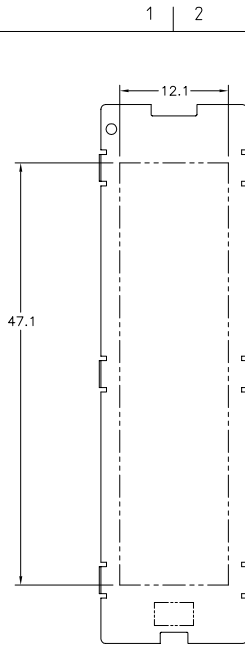
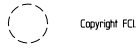
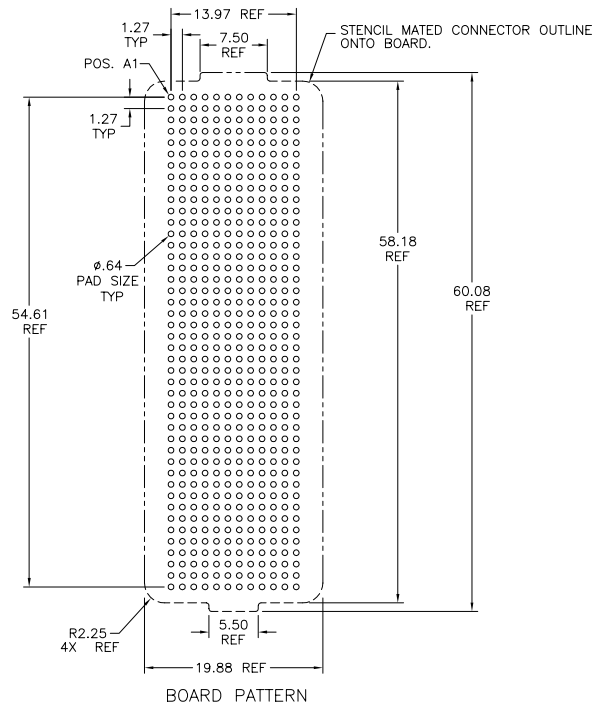


CONFIDENTIAL

mat'l code SEE NOTE 1				surface ASME Y14.5 <input checked="" type="checkbox"/> ASME Y14.5		projection 	product family MEG-ARRAY
tr	ecm no	dr	date	tolerances unless otherwise specified		MM	title
A	v03-1102	LP	10/20/03	angles	Xx3		6mm RECPT. ASSY.
B	v04-0940	VS	10/13/04		XXXB	scale 1:1	12 X 44 = 528 POS.
C	v06-0560	LP	2006/07/18	±2'	XXXX051		dwg no 10026846
		dr	D.INGRAM	04/01/03			sheet 1 of 3 size A4
		enr	D.WHITING	04/01/03			type CUSTOMER Drawing
		chr	D.WHITING	04/01/03			
		appd	D.WHITING	04/01/03			
sheet index	revision sheet	1	2	3			



FLAT AREA FOR PICK UP CAP



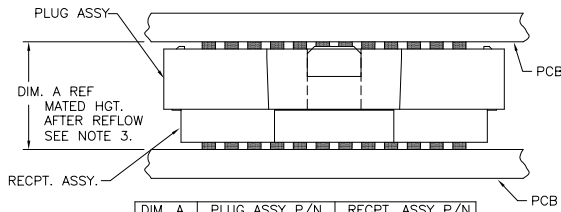
mat'l code	SEE NOTE 1	surface	ASME Y14.5	tolerance	ASME Y14.5	projection	product family
titr	ecrn no	dir	date	tolerances unless otherwise specified	angles	MM	MEG-ARRAY
c				or ±2"	°	scale 1:1	title
							6mm RECPT. ASSY. 12 X 44 = 528 POS.
		dr	D.INGRAM	04/01/03			dwg no
		engr	D.WHITING	04/01/03			sheet 2 of 3
		chr	D.WHITING	04/01/03			10026846
		appd	D.WHITING	04/01/03			A4
sheet index	revision sheet						type
							CUSTOMER Drawing

form A4mmXLC

PRODUCT NUMBER	PICK-UP CAP	CONTACT PLATING	CONTACT PLATING
10026846-001	YES	15u" (.38u") Au OVER Ni	SnPb
10026846-001LF			SnAgCu LEAD FREE (5)(6)
10026846-101	YES	30u" (.76u") Au OVER Ni	SnPb
10026846-101LF			SnAgCu LEAD FREE (5)(6)
10026846-201	YES	SEE NOTE 4.	SnPb
10026846-201LF			SnAgCu LEAD FREE (5)(6)

**NOTES:**

1. **MAT'L:**  
HOUSING: LCP  
CONTACT: COPPER ALLOY
- PLATING:**  
CONTACT: (SEE TABLE ON SHEET3)  
SOLDER BALL: (SEE TABLE ON SHEET3)  
EUTECTIC SnPb OR LEAD FREE  
95.5Sn/4Ag/0.5Cu
2. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
3. MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.
4. PLATING FOR -2XX SERIES DASH NOS: Au OVER Ni WITH SPECIAL CONTACT GEOMETRY TO MEET REQUIREMENTS OF TELCORDIA GR-1217-CORE: CENTRAL OFFICE ENVIRONMENT.
5. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION
6. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION



DIM. A	PLUG ASSY P/N	RECEPT. ASSY P/N
6.0	10022671-X02	10026846-X01

MATED HEIGHT AFTER REFLOW IS BASED ON  $\phi$  .64mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

END VIEW - MATED CONNECTORS SCALE NONE

mat'l code SEE NOTE 1		surface ASME Y14.5 <input checked="" type="checkbox"/> ASME Y14.5	tolerance ASME Y14.5	projection 	product family MEG-ARRAY
ltr	ec'n no	dr	date	title	
c				6mm RECEPT. ASSY. 12 X 44 = 528 POS.	
				scale: 1:1	
		dr	D. INGRAM 04/01/03		dwg no 10026846
		engr	D. WHITING 04/01/03		sheet 3 of 3
		chr	D. WHITING 04/01/03		size A4
		appd	D. WHITING 04/01/03		type CUSTOMER Drawing
sheet index	revision sheet				